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**ZHU et al.**(10) **Pub. No.: US 2022/0377894 A1**(43) **Pub. Date: Nov. 24, 2022**(54) **MOTHERBOARD****Publication Classification**(71) Applicants: **Inventec (Pudong) Technology Corporation**, Shanghai (CN);  
**INVENTEC CORPORATION**, Taipei (TW)(51) **Int. Cl.**  
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A motherboard including a main circuit board, a first connector, a power circuit board and a second connector. The first connector is disposed on the main circuit board. A periphery of the power circuit board is spaced apart from a periphery of the main circuit board. The second connector is disposed on the power circuit board. The first cable electrically connects the first connector with the second connector.

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